

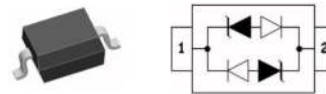
Features

Bi-directional ESD protection of one line
 Low capacitance: 0.6 pF
 Low reverse stand-off voltage: 3.3 V
 Low reverse clamping voltage
 Low leakage current
 Excellent package: 1.7mm × 1.3mm × 1.0mm
 Fast response time
 JESD22-A114-B ESD Rating of class 3B per human body model
 IEC 61000-4-2 Level 4 ESD protection



Applications

Cellular phones
 Audio and video equipment
 Handheld-Wireless Systems
 PDAs
 Ethernet – 10/100/1000 Base
 Portable electronics
 USB Interface
 Other electronics equipments communication systems



SOD-323

Absolute Maximum Rating

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air)	±30	kV
	ESD per IEC 61000-4-2 (Contact)	±30	
P_{PP}	Peak Pulse Power (8/20μs)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260	°C

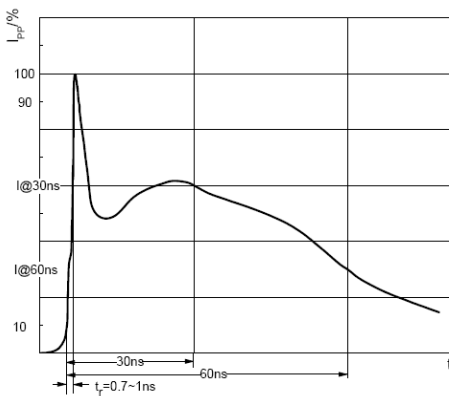
ESD standards compliance

IEC61000-4-2 Standard

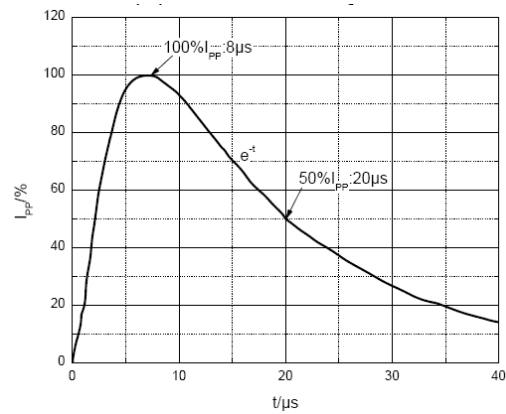
Contact Discharge		Air Discharge	
Level	Test Voltage kV	Level	Test Voltage kV
1	2	1	2
2	4	2	4
3	6	3	8
4	8	4	15

JESD22-A114-B Standard

ESD Class	Human Body Discharge V
0	0~249
1A	250~499
1B	500~999
1C	1000~1999
2	2000~3999
3A	4000~7999
3B	8000~15999



ESD pulse waveform according to IEC61000-4-2



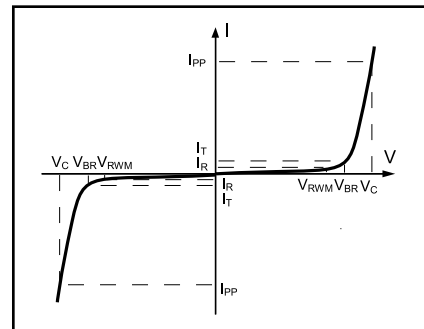
8/20µs pulse waveform according to IEC 61000-4-5

Electrical Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				3.3	V
Breakdown Voltage	V_{BR}	$I_T = 1\text{mA}$	4.0	5.0	6.0	V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3\text{V}$			0.2	μA
Clamping Voltage	V_C	$I_{PP} = 1\text{A}$ (8 x 20 μs pulse)		7	9	V
Clamping Voltage	V_C	$I_{PP} = 20\text{A}$ (8 x 20 μs pulse)		16	20	V
Junction Capacitance	C_J	$V_R = 0\text{V}$, $f = 1\text{MHz}$		1		pF

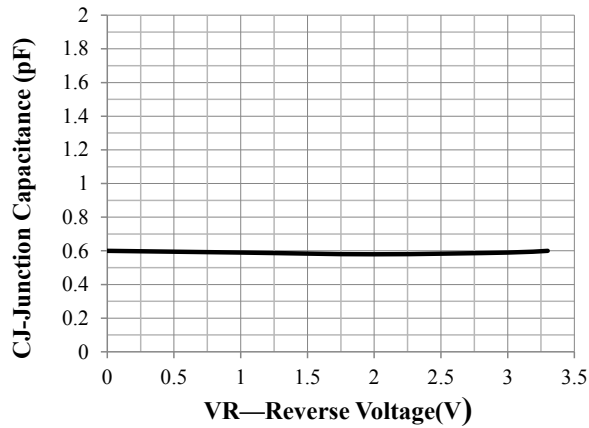
Electrical Parameter

Symbol	Parameter
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Peak Pulse Current
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage

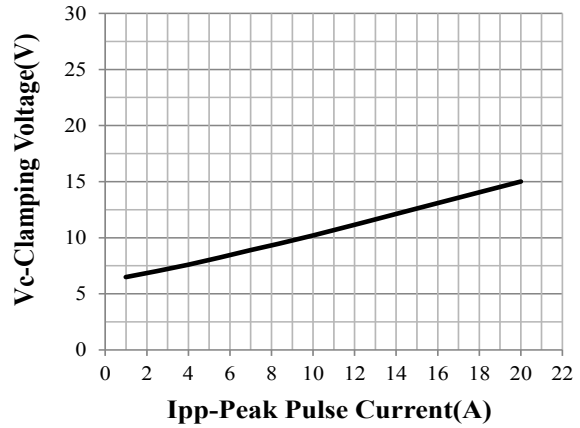


V-I characteristics for a Bi-directional TVS

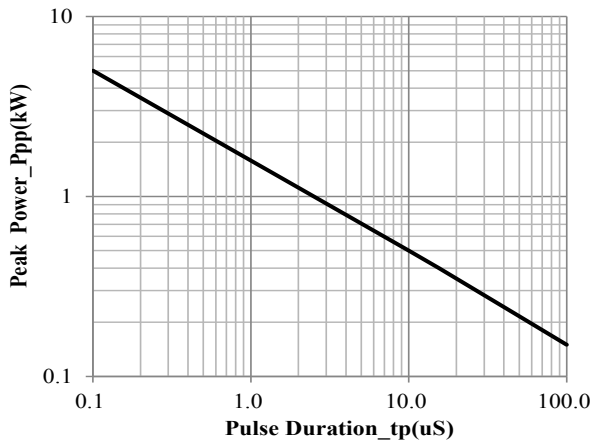
RATING AND CHARACTERISTIC CURVES



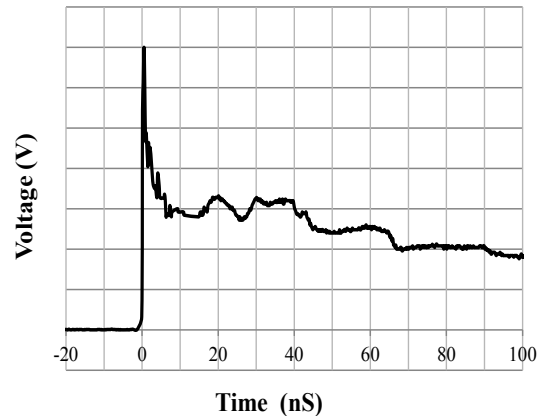
Junction Capacitance vs. Reverse Voltage



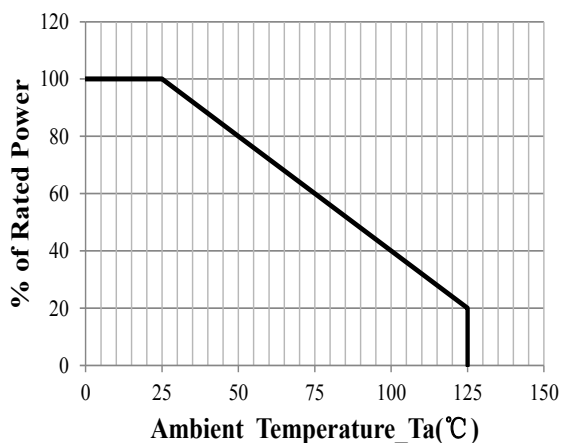
Clamping Voltage vs. Peak Pulse Current



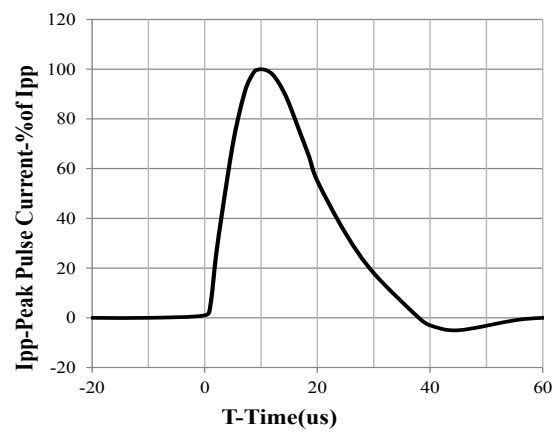
Peak Pulse Power vs. Pulse Time



IEC61000-4-2 Pulse Waveform



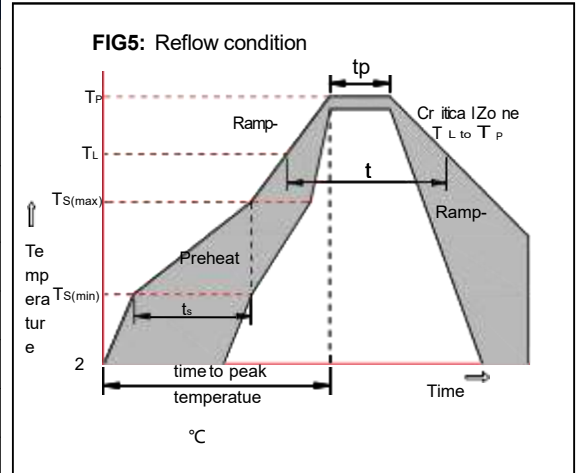
Power Derating Curve



8 X 20us Pulse Waveform

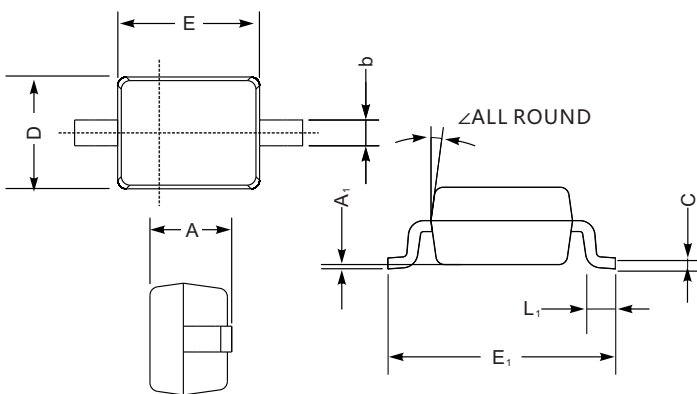
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



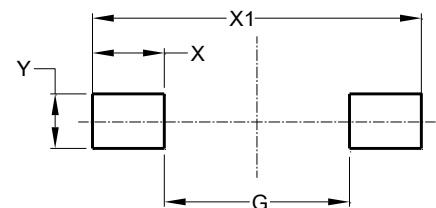
Package Dimensions & Suggested Pad Layout

SOD323



SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	z
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & reel specification

Tape		Symbol	Dimension (mm)		
		P0	4.00±0.20		
		P1	4.00±0.20		
		P2	2.00±0.20		
		D0	1.55±0.20		
		D1	1.00±0.20		
		E	1.55±0.25		
		F	3.60±0.20		
		W	8.00±0.20		
		A0	2.00±0.20		
		B0	3.25±0.20		
		K0	1.35±0.20		
		T	0.23±0.10		
		7" Reel		D2	177.0±5.0
				D3	55Min.
D4	R24.6±2.0				
G	R82.0±2.0				
I	13.0±2.0				
W1	10.20±3.0				
		Quantity: 3000PCS			